

EAST Search History**EAST Search History (Prior Art)**

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L14	26754700	@ad<="20030513"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/24 14:30
L15	9553280	(cavity hole recess\$4 opening)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/24 14:30
L16	4135635	(ic chip module electronic adj component)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/24 14:30
L17	18089	(button (finger near3 press \$4)) same L15 same L16	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/24 14:30
L18	2372	L17 and L14	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2011/10/24 14:30
L19	492	L18 and card	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2011/10/24 14:30
L20	18	19 and 235/492,380.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2011/10/24 14:33
S95	109	("2,328,654" "3,008,635" "4,303,904" "4,672,182" "4,851,650" "4,928,001" "5,477,038" "5,500,513" "5,550,734" "5,585,787" "5,844,230" "5,864,830" "5,883,377" "5,903,830" "5,917,965" "5,946,669" "5,953,710" "5,984,180" "5,984,191" "5,991,527" "6,021,943" "6,038,597" "6,039,245" "6,044,360" "6,105,009" "6,119,107" "6,138,917" "6,402,029" "6,422,462" "6,473,500" "6,502,745" "6,529,725" "6,549,912" "6,615,189"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2011/10/03 14:33

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S97	26	S95 and (sign board)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2011/10/03 14:37
S100	64103	(seal\$4 adhesive adher\$4 insulat\$4) near10 (component chip) same S99	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/06 12:31
S101	26754473	@ad<="20030513"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/06 12:32
S102	4829860	(cavity hole recess opening)	US-PGPUB; USPAT; USOCR	OR	ON	2011/10/06 12:32
S103	64103	(seal\$4 adhesive adher\$4 insulat\$4) near10 (component chip) same S102	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/06 12:32
S104	27038	S103 and S101	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/06 12:32
S105	5857	(seal\$4 adhesive adher\$4 insulat\$4) near10 (component chip) same S102 near7 (cover\$4 extend\$4 entir \$4 over) and S101	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/06 12:33
S106	53	S105 and "235".clas.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/06 12:35
S107	884	rub\$5 with (cavity hole recess) with (glue insulation)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/21 17:02
S108	13	S107 and card	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/21 17:05
S109	130	lead adj frame with (insert\$4 cavity) and (chip ic package) same card	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/21 17:06

S110	26754690	@ad<="20030513"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/21 17:06
S111	130	lead adj frame with (insert\$4 cavity) and (chip ic package) same card	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/21 17:06
S112	57	S111 and S110	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/21 17:06
S113	495724	insulat\$4 adj layer	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/21 17:10
S114	3	S112 and S113	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/21 17:11
S115	26754700	@ad<="20030513"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2011/10/22 09:49
S116	401	hybrid same card and switch \$4 and (cavity hole recess opening) and S115	US-PGPUB; USPAT; USOCR	OR	ON	2011/10/22 09:49
S117	61	S116 and "235"/\$.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; IBM_TDB	OR	ON	2011/10/22 09:50

EAST Search History (Interference)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	755027	component.clm.	US-PGPUB; USPAT	OR	ON	2011/10/24 14:22
L2	681200	substrate.clm.	US-PGPUB; USPAT	OR	ON	2011/10/24 14:22
L3	138793	chip.clm.	US-PGPUB; USPAT	OR	ON	2011/10/24 14:22
L4	389133	insulat\$4.clm.	US-PGPUB; USPAT	OR	ON	2011/10/24 14:22
L5	136307	rub\$5.clm.	US-PGPUB; USPAT	OR	ON	2011/10/24 14:23
L6	22	1 and 2 and 3 and 4 and 5	US-PGPUB; USPAT	OR	ON	2011/10/24 14:23

L7	8111	(rub rubbing).clm.	US-PGPUB; USPAT	OR	ON	2011/10/24 14:24
L8	0	1 and 2 and 3 and 4 and 7	US-PGPUB; USPAT	OR	ON	2011/10/24 14:24
L9	8953	(rub rubbing rubbed).clm.	US-PGPUB; USPAT	OR	ON	2011/10/24 14:24
L10	0	1 and 2 and 3 and 4 and 9	US-PGPUB; USPAT	OR	ON	2011/10/24 14:24
L11	1250991	(substrate layer).clm.	US-PGPUB; USPAT	OR	ON	2011/10/24 14:25
L12	2	1 and 11 and 3 and 9	US-PGPUB; USPAT	OR	ON	2011/10/24 14:25

10/24/2011 2:35:12 PM

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